



HSA733

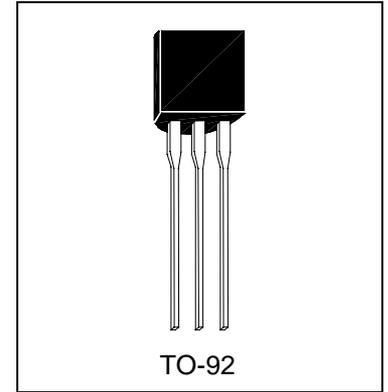
PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HSA733 is designed for use in driver stage of AF amplifier applications.

Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 250 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -60 V
VCEO Collector to Emitter Voltage -50 V
VEBO Emitter to Base Voltage -5 V
IC Collector Current -100 mA
IB Base Current -20 mA



Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-60	-	-	V	IC=-100uA, IE=0
BVCEO	-50	-	-	V	IC=-1mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-0.1	uA	VCB=-60V, IE=0
IEBO	-	-	-0.1	uA	VEB=-5V, IC=0
*VCE(sat)	-	-0.18	-0.3	V	IC=-100mA, IB=-10mA
VBE(on)	-0.55	-0.62	-0.7	V	VCE=-6V, IC=-1mA
*hFE	90	200	600		VCE=-6V, IC=-1mA
fT	100	180	-	MHz	VCE=-6V, IC=-10mA
Cob	-	4.5	6	pF	VCB=-10V, f=1MHz, IE=0

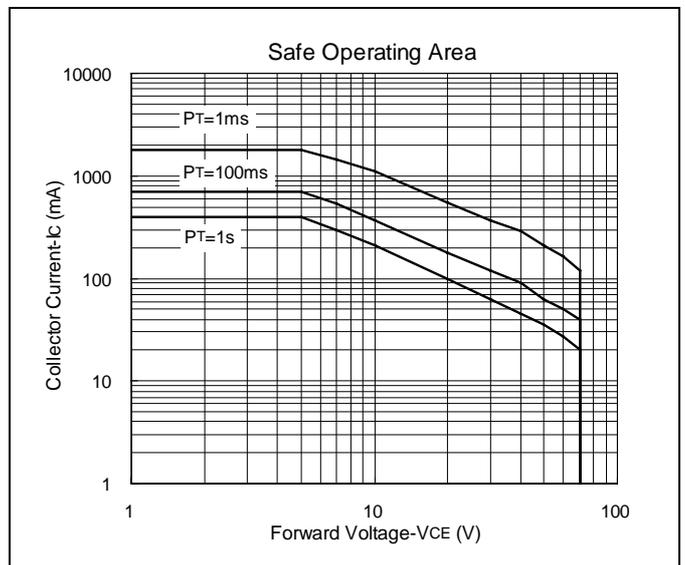
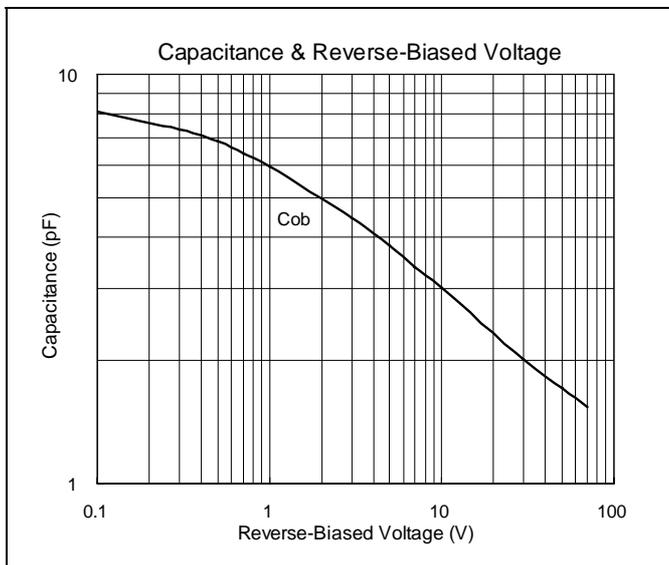
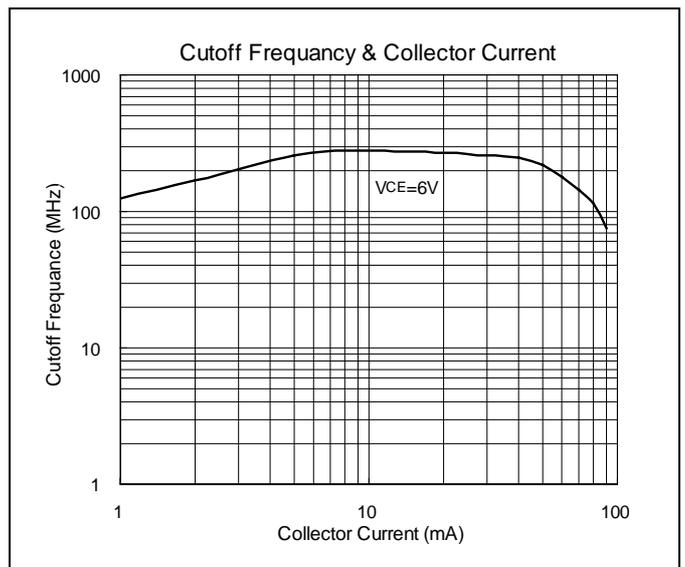
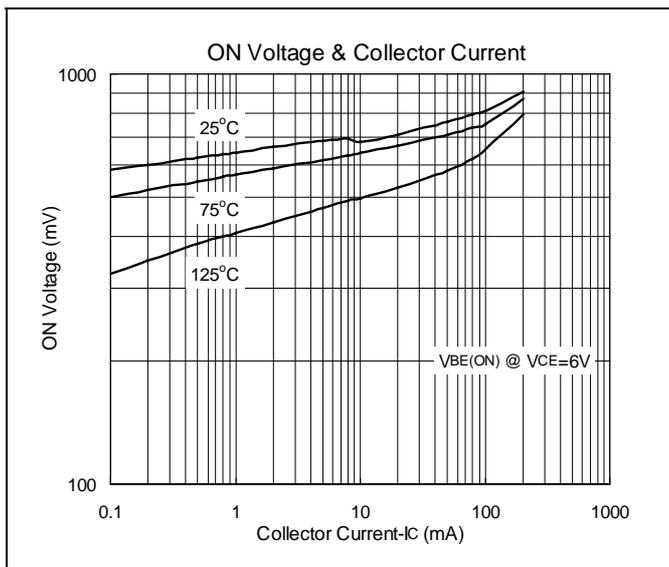
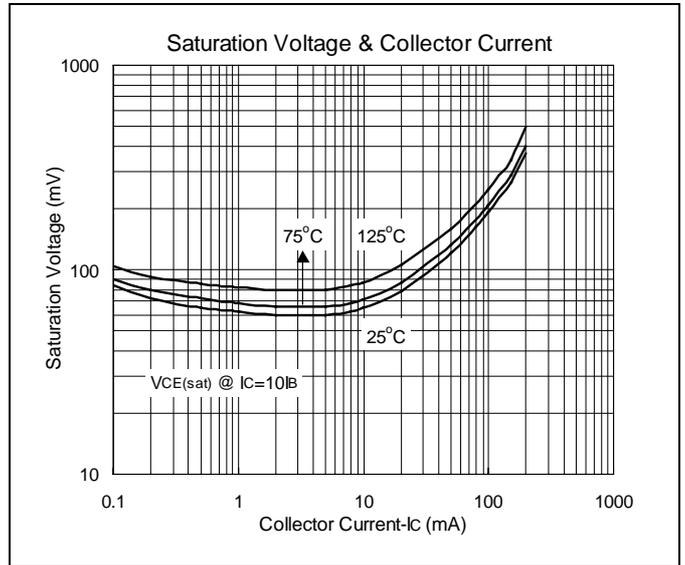
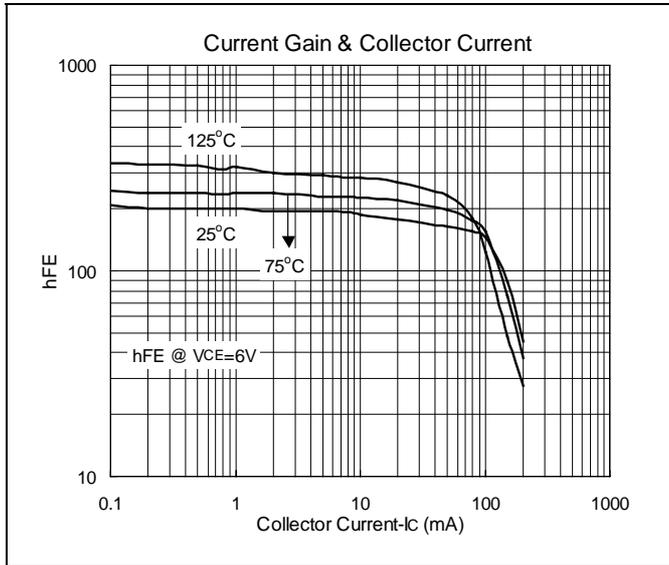
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

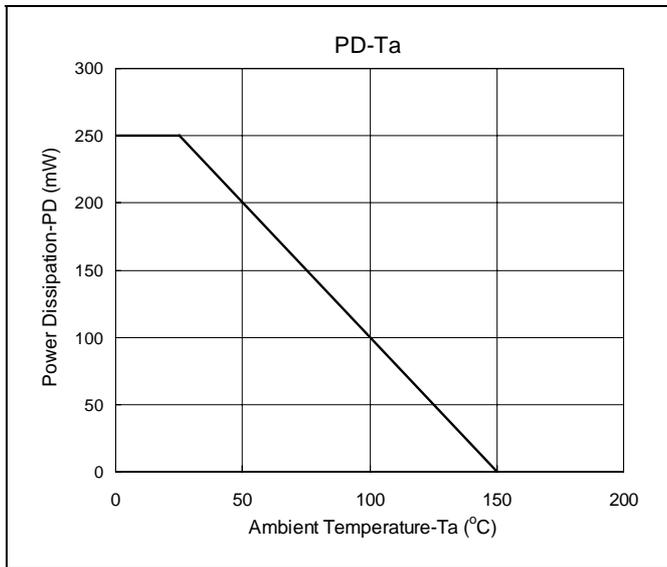
Classification Of hFE1

Rank	R	Q	P	K
Range	90-180	135-270	200-400	300-600



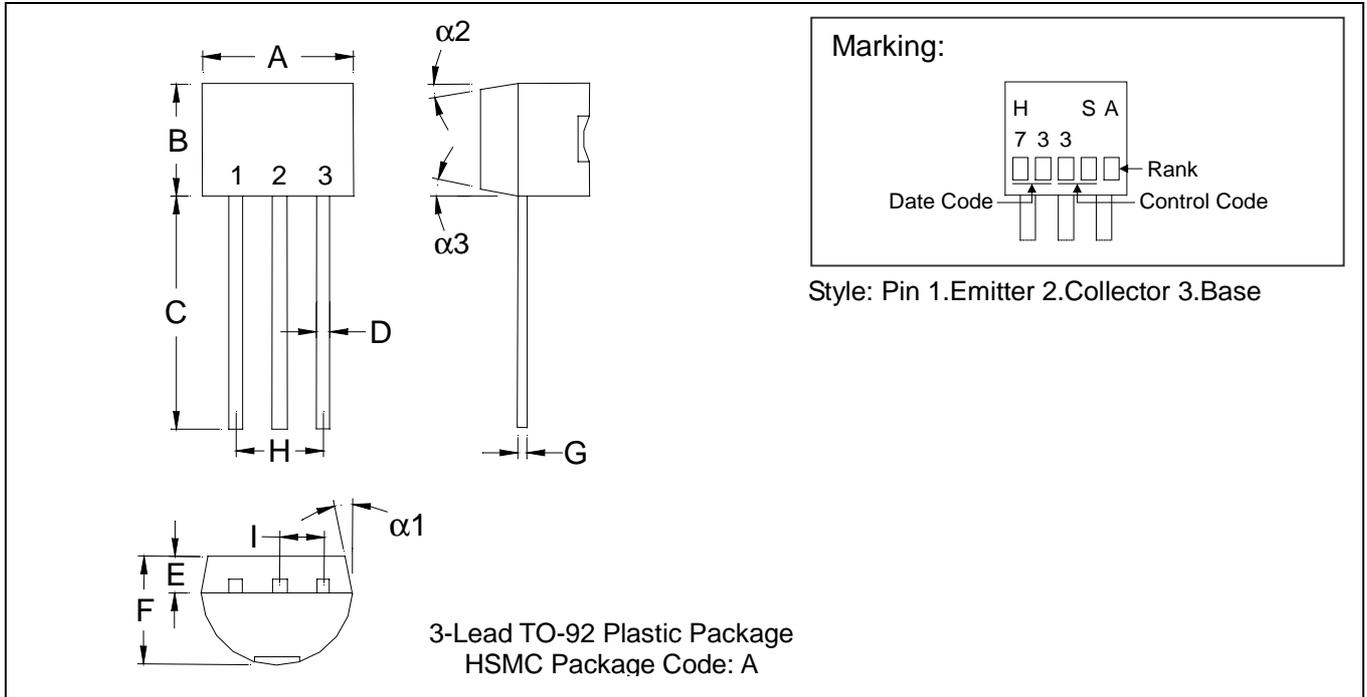
Characteristics Curve







TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
Tel : 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
Tel: 886-3-5983621~5 Fax: 886-3-5982931